

Triacs

(0.8 - 25 Amps)

General Description

These gated triacs from Teccor Electronics are part of a broad line of bidirectional semiconductors. The devices range in current ratings from 0.8 to 25 amperes and in voltages from 200 to 800 volts.

The triac may be gate triggered from a blocking to conduction state for either polarity of applied voltage and is designed for AC switching and phase control applications such as speed and temperature modulation controls, lighting controls and static switching relays. The triggering signal is normally applied between the gate and MT1.

Teccor's gated triacs are available in a choice of different packages as shown above. Isolated packages are offered with internal construction, having the case or mounting tab electrically isolated from the semiconductor chip. This feature facilitates the use of low-cost assembly and convenient packaging techniques. Tape-and-reel capability is available. See "Packing Options" section of this catalog.

All Teccor triacs have glass-passivated junctions to ensure long term device reliability and parameter stability. Teccor's glass offers a rugged, reliable barrier against junction contamination. Variations of devices covered in this data sheet are available for custom design applications. Please consult factory for more information.

Features

- Electrically-isolated packages
- Glass-passivated junctions
- Voltage capability up to 800 Volts
- Surge capability up to 200 Amps

		Part N	lumber													
T(RMS)		Isolated	Non-Is	olated	VDRM			let				IDRM		VTM	V	37
RMS On-State Current Conduction Angle of 360° (4)	MT1 G MT2	MT2 MT2			Repetitive Peak Blocking Voltage (1)	repetitive Peak In Specific Operating Quadrants Voltage VD Cate Trigger Current in Specific Operating Quadrants VD = 12VDC			,	eak Off-St Current Gate Ope DRM = Ma Rated Valu (1) (16)	n ax	Peak On-State Voltage at Max Rated RMS Current T _C = 25 °C (1) (5)	DC Gate Trigger Voltage $V_D = 12VDC$ $R_L = 60\Omega$ (2) (6) (18)			
(4)		MT2 THERMOTAB	MT1UUUG MT2	MT2				mAmp	s	I	T _C =	mAmps	T =	_	Vo	_
	TO-92	TO-220AB	TO-202AB	TO-220AB	Volts	QI	QII	QIII	QIV	QIV	25°C	T _C = 100°C	T _C = 125 C	Volts	T _C = 125°C	T _C = 25°C
MAX	See "F	-	nensions" sec ations.	tion for	MIN		M.	AX		TYP		MAX		MAX	MIN	MAX
1170	OZXBE3	70.11			208	10	10	10		25	.02	0.5	1.0	1.6	6.2	2.0
	CAPES.				400	10	10	10	-	25	.02	0.5	1.0	1.6	0.2	2.0
1					500	10	10	10		25	02	0,8 0.5	1,0	1.6	0.2	2.0
1.8	00000				606	10	10	10		25	.02	0.5	1.0	1.6	0.2	2.0
Amp	77.064					25		26						A THE RESERVE AND ADDRESS OF THE PARTY OF TH		M. House, it was to be a facility of
	CALCULATION SHIPS AND ASSESSMENT				200		25	Septiment of the septim		50	.02	0,5	1.0	1.8	0.2	2.5
	OAXEE4				400	25	25	25		50	.02	0.5	1.0	1.6	0.2	2.5
	CANCEL				500	25	25	25		50	.02	0.5	1.0	1,6	0,2	2.5
	CEXTER				600	25	25	25		50	.02	0.5	1.0	1.0	0.2	2.8
	Q201E3				200	10	10	10		25	.02	0.5	1.0	1.6	0.2	2.0
	Q401E3				400	10	10	10		25	.02	0.5	1.0	1.6	0.2	2.0
1.0	Q501E3				500	10	10	10		25	.02	0.5	1.0	1.6	0.2	2.0
Amp	Q601E3		į į		600	10	10	10		25	.02	0.5	1.0	1.6	0.2	2.0
	Q201E4				200	25	25	25		50	.02	0.5	1.0	1.6	0.2	2.5
	Q401E4				400	25	25	25		50	.02	0.5	1.0	1.6	0.2	2.5
	Q501E4		,		500	25	25	25		50	.02	0.5	1.0	1.6	0.2	2.5
ı İ	Q601E4				600	25	25	25		50	.02	0.5	1.0	1.6	0.2	2.5
		Q2004L3	Q2004F31		200	10	10	10		25	.05	0.5	2.0	1.6	0.2	2.0
		0400413	Q4004F31		400	10	10	10		25	.05	0.5	2.0	1.6	0.2	2.0
		OSCOLUT	Q5004F31		500	10	10	10		25	.05	0.5	2.0	1.6	0.2	2.0
4.0		2600413	COUNTY		800	10	10	10		28	.05	0.5	2.0	1.6	0.2	2.0
Anns		G20e4L4	Q2004F41		200	25	25	25		50	- 05	0.5	2.0	1.6	0.2	2.5
		CAROLLA	Q4004F41		400	25	25	25	-	80	.05	0.5	2.0	1.6	0.2	2.5
		Q5004L4	Q5004F41		500	25	25	25	-	50	.05	0.5	2.0	1.6	0.2	2.5
		Concess	GBR04F41		600	25	25	25		50	.05	0.5	2.0	1.0	0.2	2.5
		GTODALA	Anona at		790	25	25	25		50	.95	0.5	2.0		0.2	
								25						1.6		2.5
		O8004L4	Q2006F41	0200004	800	25	25	0.0000000000000000000000000000000000000		50	.05	0.8	2.0	1.6	0.2	2.5
		Q2006L4		Q2006R4	200	25	25	25		50	.05	0.5	2.0	1.6	0.2	2.5
6.0		Q4006L4	Q4006F41	Q4006R4	400	25	25	25	L	50	.05	0.5	2.0	1.6	0.2	2.5
Amps		Q5006L4	Q5006F41	Q5006R4	500	25	25	25	ļ	50	.05	0.5	2.0	1.6	0.2	2.5
/ps		Q6006L5	Q6006F51	Q6006R5	600	50	50	50		75	.05	0.5	2.0	1.6	0.2	2.5
		Q7006L5		Q7006R5	700	50	50	50		75	.05	0.5	2.0	1.6	0.2	2.5
SHIP CONTRACTOR CONTRA	THE SHAPE SHOW CHARLES	Q8006L5		Q8006R5	800	50	50	50		75	.05	0.5	2.0	1.6	0.2	2.5
		Q2008L4	Q2008F41	Q2008R4	200	25	25	25		50	.05	0.5	2.0	1.6	0.2	2.5
		CARRELA	Q4008F41	Q4008R4	490	25	28	25		50	.86	0.5	2.0	1.6	0.2	2.5
8.0		October 4	CHOUSE	Q5068R4	500	25	25	26		50	.05	0.5	2.0	1,6	0.2	2.5
Amps		QUOTELS	GEOREFS1	Ceaters	600	50	50	50		75	.05	0.5	2.0	1.6	0.2	2.5
WITH CALL STATE OF THE SHOPE OF		できたなるがなる。				TOTAL PROPERTY.			PHONE STATE	100	Manual Control of the	TO STORY OF THE STORY			SHOWE ASSESSMENT	
		Q7000L5		Q7666R5	700	50	50	50		75	.05	0,5	2.0	1,6	0.2	2.5

See General Notes and Electrical Specification Notes on page 2-4.

14	lem	Peu	P _{G(AV)}	In	144	dv/dt (c)	dv	dt	l _{igt}	14	dilat
Holding Current (DC) Gate Open (1) (8) (12)	rrent Gate Gate Peak Gate Average Power Dis- Den Current sipation Dissipation		Peak One C		Critical Rate-of-Rise of Commutation Voltage at Rated V _{DRM} and I _{T(RMS)} Commutating di/dt = 0.54 Rated I _{T(RMS)} /ms Gate Unenergized (1) (4) (13)	Critical Rate-of- Rise of Off-State Voltage at Rated V _{DRM} Gate Open (1)		Gate Controlled Turn-On Time I _{GT} = 200mA 0.1µs Rise	RMS Surge (Non- Repetitive) On-State Cur- rent for Period of 8.3ms for	Maximum Rate-of- Change of On-State Cui rent I _{GT} = 200mA with 0.1µs	
							Volts/	uSec	Time	Fusing	Rise Time
mAmps				Am	nne	Volts/µSec	T _C = 100°C	T _C =	(10) μSec		
пипро						νοκοιμούο	100.0	1200	μοσο	-	
MAX	Amps	Watts	Watts	60Hz	50Hz	TYP	MI		TYP	Amp ² Sec	Amps/μSec
15	1.0	10	0.2	10	8.3	1,0	40	36	2.5	0.41	70
15	1,0	10	0.2	10	8,3	1,0	35	25	2,5	0.41	20
16	1.0	10	0.2	10	8.3	1.0	30	20	2,6	0.41	20
15	1.0	10	0.2	10	8.3	1;0 2.0	25 50	15	2.5	0.41	70
25	1.0	10		10	8,3			40	3	0.41	20
26	1.0	10	0.2	10	8.3	2.0	45	35	3	0.41	20
25	1.0	10	0.2	10	8.3	2.0	40	30	3	0.41	20
25	1.0	10	0,2	10	8.3	2.0	35	25	3	0.41	20
15	1.0	10	0.2	20	16.7	1.0	40	30	2.5	1.6	30
15	1.0	10	0.2	20	16.7	1.0	40	30	2.5	1.6	30
15	1.0	10	0.2	20	16.7	1.0	30	20	2.5	1.6	30
15	1.0	10	0.2	20	16.7	1.0	30	20	2.5	1.6	30
25	1.0	10	0.2	20	16.7	1.0	50	40	3	1.6	30
25	1.0	10	0.2	20	16.7	1.0	50	40	3	1.6	30
25	1.0	10	0.2	20	16.7	1.0	40	30	3	1.6	30
25	1.0	10	0.2	20	16.7	1.0	40	30	3	1.6	30
20	1.2	15	0.3 0.3	55	46 45	2.0 2.0	50 50	40	2.5 2.5	12.5 12.5	30
20	1.2	15	0.3	55 55	46	2.0		40			50 50
20	1.2		0.3		46		40	30 30	2.5	12.6 12.5	50
20	1.2	15 15	0.3	95	48	2.6	100	75	3	12.5	
30 30	1.2	15	0.3	55 56	46	2.0	100	73		12.5	50
30	1.2	15	0.3	56 56	46	2.0	75	50	3	12.5	50 50
30	13	15	0.3	55	46	2.0	75	50	3	12.5	50
30	1.2	15	0.3	55 55	46	2.0	86	40	3	12.5	50
30	1.2	15	0.3	55	48	2.0	60	40	3	12.5	58
50	1.6	18	0.5	80	65	4.0	200	120	3	26.5	70
50	1.6	18	0.5	80	65	4.0	200	120	3	26.5	70
50	1.6	18	0.5	80	65	4.0	150	100	3	26.5	70
50	1.6	18	0.5	80	65	4.0	150	100	3	26.5	70
50	1.6	18	0.5	80	65	4.0	125	85	3	26.5	70
50	1.6	18	0.5	80	65	4.0	125	85	3	26.5	70
50	1.8	20	0.5	100	83	4.0	250	150	3	41	70
50	1.8	20	0.5	100	83	4.0	250	150	3	41	70
50	1.8	20	0,5	100	83	4.0	220	125	3	44	70
50	1.8	20	0.5	100	83	4.0	220	125	3	41	70
50	1.8	20	0.5	100	83	4.6	150	100	3	44	70
50	1.8	20	0.5	100	83	4.0	150	100	3	44	70
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See General Notes and Electrical Specification Notes on page 2-4.

l _{it} (rojs)	Isolated	Part Number	olated	V _{DRM}			lor				lonu		¥	G)
RMS On-State Current Conduction Angle of 360° (4) (16)	MT1UUG G	MT2 MT1 MT1 MT3 MT3	MT2 MT1 MT2	Repeti- tive Peak Blocking Voltage (1)		DC Gate Trigger Current In Specific Operating Quadrants V _D = 12VDC (3) (7) (15) Peak Off-State Cu Gate Open V _{DRM} = Rated Value (1) (16)		_M = Max ue	tt DC Gate Trig- ger Voltage V _D = 12VDC (2) (6) (15) (18)					
	THERMOTAB					<u>r</u>	nAmp:	s	1	T	mAmps			olts
	TO-220AB	TO-202AB	TO-220AB	Volts	Qi	QII	QIII	QIV	QIV	T _C = 25°C	T _C =	T _C = 125°C	T _C ≈ 125°C	T _C =
MAX	See "Package	Dimensions" section fo	r variations.	MIN		M	ΑX		TYP		MAX		MIN	MAX
	Q2010L5	Q2010F51	Q2010R8	200	50	50	50		75	.05	0.6	2.0	0.2	2.5
10,0	Q4010L5	Q4919751	Q4010R5	400	30	10	50		7.5	.05	0,5	2.0	0.2	2.5
Amps	CEONOLS	CEO10F81	CBOTOKS	500	- 3	30	5		77	.00	1.6	2.0		2.5
	Geneta	Q5010F91	Q8010R5	600		- 60	5		78	.05	8.5	20	0.2	2.5
	C7010L5		Q7010R5	700	-50	90			78	.06	9.5	2.0	0.2	2.5
	080101.5		Q8010R5	800	58	50	50		7.5	0.1	0.5	2.0	92	2.5
	Q2015L5		Q2015R5	200	50	50	50			.05	0.5	2.0	0.2	2.5
15.0 [Q4015L5		Q4015R5	400	50	50	50			.05	0.5	2.0	0.2	2.5
Amps	Q5015L5		Q5015R5	500	50	50	50			.05	0.5	2.0	0.2	2.5
	Q6015L5		Q6015R5	600	50	50	50			.05	0.5	2.0	0.2	2.5
	Q7015L5		Q7015R5	700	50	50	50			0.1	1.0	3.0	0.2	2.5
	Q8015L5		Q8015R5	800	50	50	50			0.1	1.0	3.0	0.2	2.5
			Q2025R5	200	50	50	50			0.1	1.0	3,0	0.2	2.5
25.0			Q4025R8	400	34	59	50			0.1	1.0	3.0	9.2	2.6
Amps			Q6025R5	500	50	50	50			0.1	1.0	3.0	0.2	2.5
			Q6025R8	690	54	30	50			0.1	1.0	3.0	0.2	2.5
			C17025R5	700	50	50	膀			0.1	1,0	1.0	0.2	2.5
			Q8025R8	800	150	30	50			0.1	1 1.0	3.0	1 02	1.5

General Notes

- All measurements are made at 60 Hz with a resistive load at an ambient temperature of +25°C unless specified otherwise.
- Operating temperature range (T_{.I}) is -65°C to +125°C for TO-92, and -40°C to +125°C for all other devices
- Storage temperature range (T_S) is -65°C to +150°C for TO-92, and -40°C to +150°C for TO-202 devices, and -40°C to +125°C for all other devices.
- Lead solder temperature is a maximum of 230°C for 10 seconds, maximum; ≥ 1/16" (1.59mm) from case
- The case temperature (T_C) is measured as shown on the dimensional outline drawings. See "Package Dimensions" section of this catalog.

Electrical Specification Notes

- (1) For either polarity of MT2 with reference to MT1 terminal.
- For either polarity of gate voltage (V_{GT}) with reference to MT1
- See Definition of Quadrants.
- See Figures 2.1 through 2.7 for current rating at specific operating
- See Figures 2.8 through 2.10 for i_T vs v_T
- (6) See Figure 2.12 for V_{GT} vs T_C.
- (7) See Figure 2.11 for I_{GT} vs T_C.
- (8) See Figure 2.14 for I_H vs T_C.
- (9) See Figure 2.13 for surge rating with specific durations.
- (10) See Figure 2.15 for t_{gt} vs I_{GT}.
- (11) See package outlines for lead form configurations. When ordering special lead forming, add type number as suffix to part number.
- (12) Initial on-state current = 200mA(DC) for 1-10 amp devices, 400 mA(DC) for 15 amp to 25 amp devices.
- (13) See Figures 2.1 through 2.6 for maximum allowable case temperature at maximum rated current.
- (14) Pulse width ≤ 10µs.
- (15) $R_L = 60\Omega$ for 0.8-10 amp triacs; $R_L = 30\Omega$ for 15-25 amp triacs.
- (16) $T_C = T_J$ for test conditions in off-state.
- (17) IGT=500 mA for 25 amp devices.
- (18) Quadrants I, II, and III only.

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VTM	141	leni	Pen	PC(AV)	1	M.	dv/dt(e)	de	lat	tot	A	dia		
Peak On- State Voltage at Maximum	Holding Current (DC) Gate	Peak Gate Trigger Current (14)	Peak Gate Power Dissipation	Average Gate Power	Pe One-t Su	ak Cycle rge	Critical Rate-of-Rise of Commutation Voltage at Rated	Critical Rate-of- Rise of Off-State Voltage at Rated		Gate Controlled Turn-On	RMS Surge (Non-	Maximum Rate-of- Change of		
Rated RMS Current T _C = 25°C (1) (5)	Open (1) (8) (12)		(14) I _{GT} ≤ I _{GTM}	Dissipa- tion	(9) (13)		2.00.pu		V _{DRM} & I _{T(RMS)} Commutating di/dt = 0.54 Rated I _{T(RMS)} /ms	V _{DRM} Ga (1		Time I _{GT} = 200mA 0.1µs Rise Time	Repeti- tive) On- State for Period of	On-State Current I _{GT} = 200mA with 0.1µs
(1)(3)					Am	ips	Gate Unenergized (1) (4) (13)	Volts/		(10) (17)	8.3ms For Fusing	Rise Time		
Volts	mAmps	Amps	Watts	Watts	60Hz	50Hz	Volts/μSec	T _C = 100°C	T _C = 125°C	μSec	Amps ² Sec	Amps/μSec		
MAX	MAX						TYP	M	IN	TYP				
1.6	50	1.8	20	0.5	120	100	4	350	225	3	-	70		
1.8	50	1.3	20	0.5	120	100	4	359	-25	•		70		
1.5	50	1.5	20	9,5	129	100		300		3	- 10	70		
1.5		1.8	20	0.5	120	100	4	300	200	•		70		
1.6	50	1.8	20	0.5	120	100	•	250	175		•	10		
1.6	50	1.8	20	0.5	120	198	•	250	175	- 3	60	70		
1.6	70	2.0	20	0.5	200	167	4	400	275	4	166	100		
1.6	70	2.0	20	0.5	200	167	4	400	275	4	166	100		
1.6	70	2.0	20	0.5	200	167	4	350	225	4	166	100		
1.6	70	2.0	20	0.5	200	167	4	350	225	4	166	100		
1.6	70	2.0	20	0.5	200	167	4	300	200	4	166	100		
1.6	70	2.0	20	0.5	200	167	4	300	200	4	166	100		
1.8	100	2.0	20	0.5	200	167	4	400	275	4	220	100		
1.8	100	2.0	20	0.5	200	187		400	276	4	200	200		
1.8	100	2.0	20	0,5	200	167		150	225	4	220			
1.8	100	2.0	20	0.5	200	167	•	350	225	•	228	100		
1.8	100	2.0	24)	0.5	200	167		300	200	4	220	100		
1,8	100	2.0	20	0.5	200	167		300	200	4	720	100		

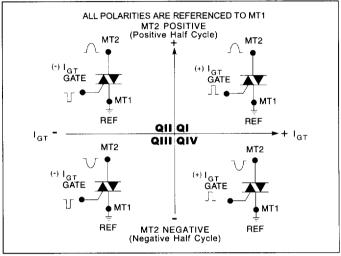
Gate Characteristics

Teccor triacs may be turned on between gate and MT1 terminals in the following ways:

- With in-phase signals (using standard AC line) Quadrants I and III are used.
- By applying unipolar pulses (gate always positive or negative)—with negative gate pulses Quadrants II and III are used and with positive gate pulses Quadrants I and IV are used.

However, due to higher gate requirements for Quadrant IV, it is recommended that only negative pulses be applied. If positive pulses are required, see sensitive triac sections of catalog or contact factory.

In all cases, if maximum surge capability is required, pulses should be a minimum of one magnitude above I_{GT} rating with a steep rising waveform (≤ 1 µsec rise time).



Definition of Quadrants

Electrical Isolation

Teccor's isolated triac packages will withstand a minimum high potential test of 2500VAC (RMS) from leads to mounting tab, over the operating temperature range of the device. See isolation table below for standard and optional isolation ratings.

ELECTRICAL FROM LEADS TO	LISOLATION MOUNTING TAB
VAC (RMS)	Isolated ** TO-220AB
2500	Standard
4000	Optional *

^{*} For 4000V isolation, use V suffix in part number.

	THI	ERMAL RESISTAL Rejc [Rej	NCE (STEADY STA)] (TYP.) °C/W	ATE)	
Туре					
	TO-92	TYPE 1 TO-202AB	TYPE 2 TO-202AB	THERMOTAB TO-220AB	NON-ISOLATED TO-220AB
0.8 Amp	60 [135]				
1.0 Amp	50 [95]				
4.0 Amps		3.5 [45]	6 [70]	3.6 [50]	
6.0 Amps		3.8		3.3	2.1 [45]
8.0 Amps		3.3		2.8	1.8
10.0 Amps		3.5		2.6	1.5
15.0 Amps				2.1	1.3
25.0 Amps					1.1

^{**} UL Recognized File E71639

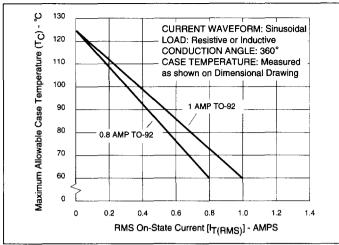


Figure 2.1 Maximum Allowable Case Temperature vs On-State Current (0.8 and 1.0 Amp)

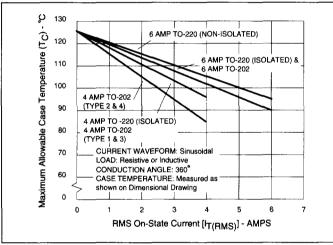


Figure 2.2 Maximum Allowable Case Temperature vs On-State Current (4 and 6 Amp)

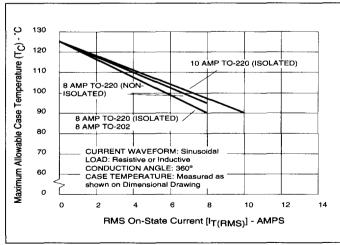


Figure 2.3 Maximum Allowable Case Temperature vs On-State Current (8 and 10 Amp)

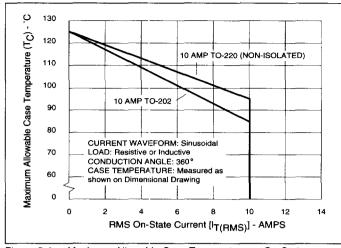


Figure 2.4 Maximum Allowable Case Temperature vs On-State Current (10 Amp)

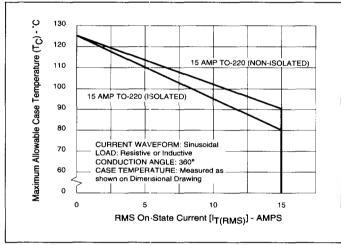


Figure 2.5 Maximum Allowable Case Temperature vs On-State Current (15 Amp)

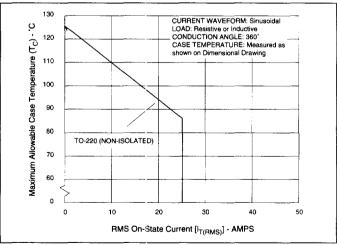


Figure 2.6 Maximum Allowable Case Temperature vs On-State Current (25 Amp)

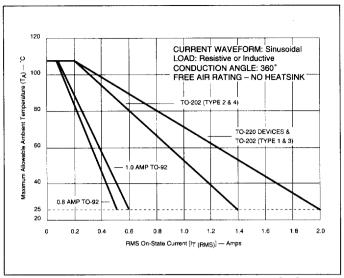


Figure 2.7 Maximum Allowable Ambient Temperature vs On-State Current

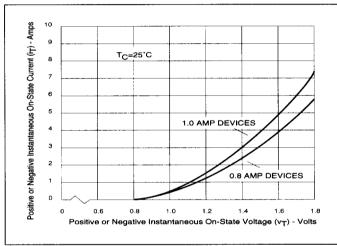


Figure 2.8 On-State Current vs On-State Voltage (Typical) (0.8 and 1.0 Amp)

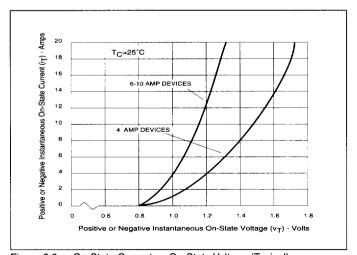


Figure 2.9 On-State Current vs On-State Voltage (Typical) (4, 6, 8, and 10 Amp)

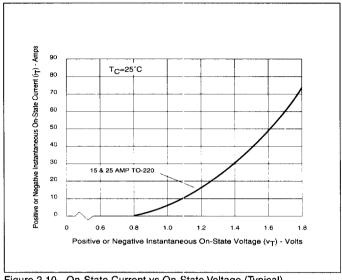


Figure 2.10 On-State Current vs On-State Voltage (Typical) (15 and 25 Amp)

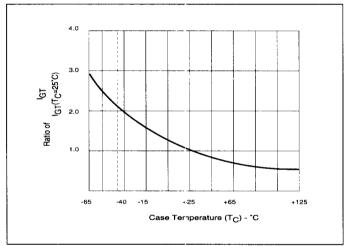


Figure 2.11 Normalized DC Gate Trigger Current for All Quadrants vs Case Temperature

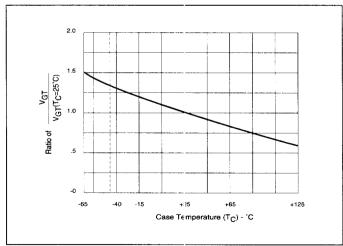


Figure 2.12 Normalized DC Gate Trigger Voltage for All Quadrants vs Case Temperature

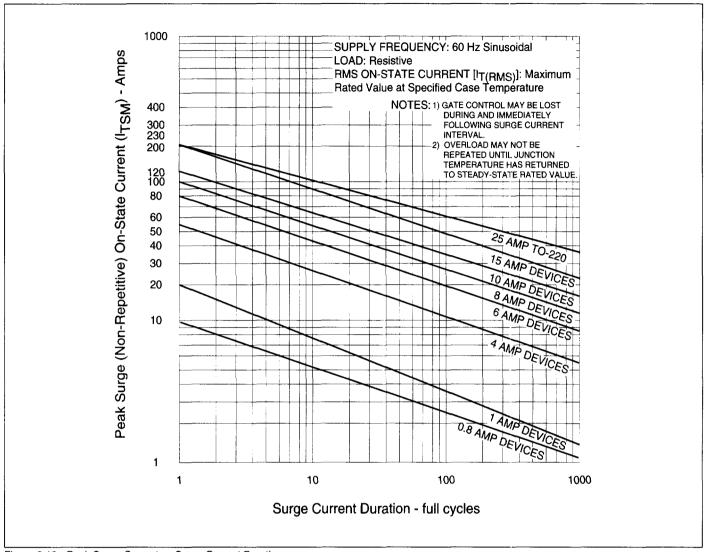


Figure 2.13 Peak Surge Current vs Surge Current Duration

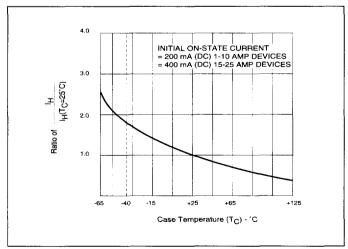


Figure 2.14 Normalized DC Holding Current vs Case Temperature

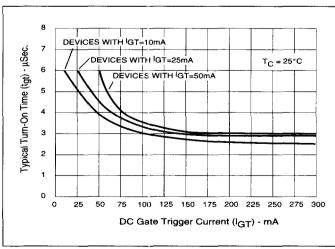


Figure 2.15 Turn-On Time vs Gate Trigger Current (Typical)

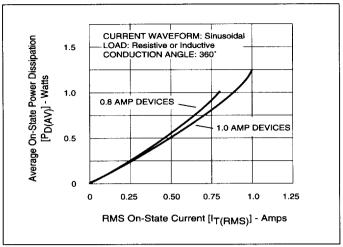


Figure 2.16 Power Dissipation (Typical) vs On-State Current (0.8 and 1.0 Amp)

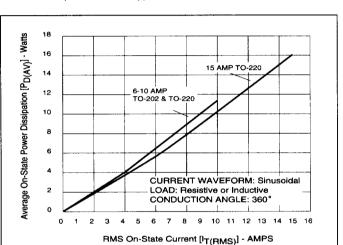


Figure 2.17 Power Dissipation (Typical) vs On-State Current (6-10 and 15 Amp)

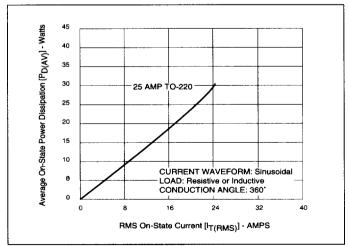


Figure 2.18 Power Dissipation (Typical) vs On-State Current (25 Amp)

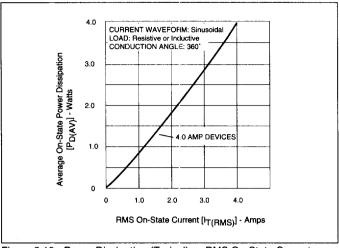


Figure 2.19 Power Dissipation (Typical) vs RMS On-State Current (4 Amp)